



Material Content Data Sheet



Sales Product Name		TLE9879QXA20		Issued		28. June 2015		
MA#		MA001370614						
Package		PG-VQFN-48-31		Weight*		129.96 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.821	3.71	3.71	37093	37093
leadframe	inorganic material	phosphorus	7723-14-0	0.018	0.01		138	
	non noble metal	zinc	7440-66-6	0.072	0.06		551	
	non noble metal	iron	7439-89-6	1.433	1.10		11028	
wire	non noble metal	copper	7440-50-8	58.193	44.77	45.94	447766	459483
	non noble metal	copper	7440-50-8	0.619	0.48	0.48	4765	4765
	encapsulation	organic material	carbon black	1333-86-4	0.181	0.14		1394
	plastics	epoxy resin	-	7.668	5.90		59004	
	inorganic material	silicondioxide	60676-86-0	52.531	40.42	46.46	404198	464596
leadfinish	non noble metal	tin	7440-31-5	2.596	2.00	2.00	19978	19978
plating	noble metal	silver	7440-22-4	0.614	0.47	0.47	4723	4723
glue	plastics	epoxy resin	-	0.280	0.22		2153	
	noble metal	silver	7440-22-4	0.937	0.72	0.94	7209	9362
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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